

7

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PCT/US98/21869

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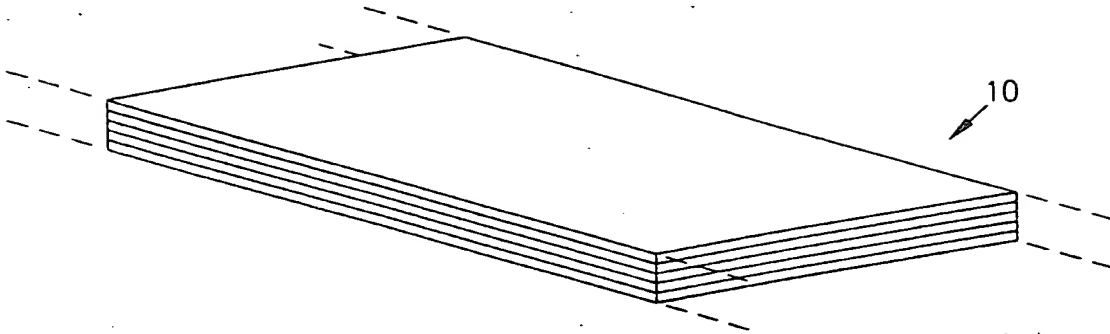


FIG. 1A

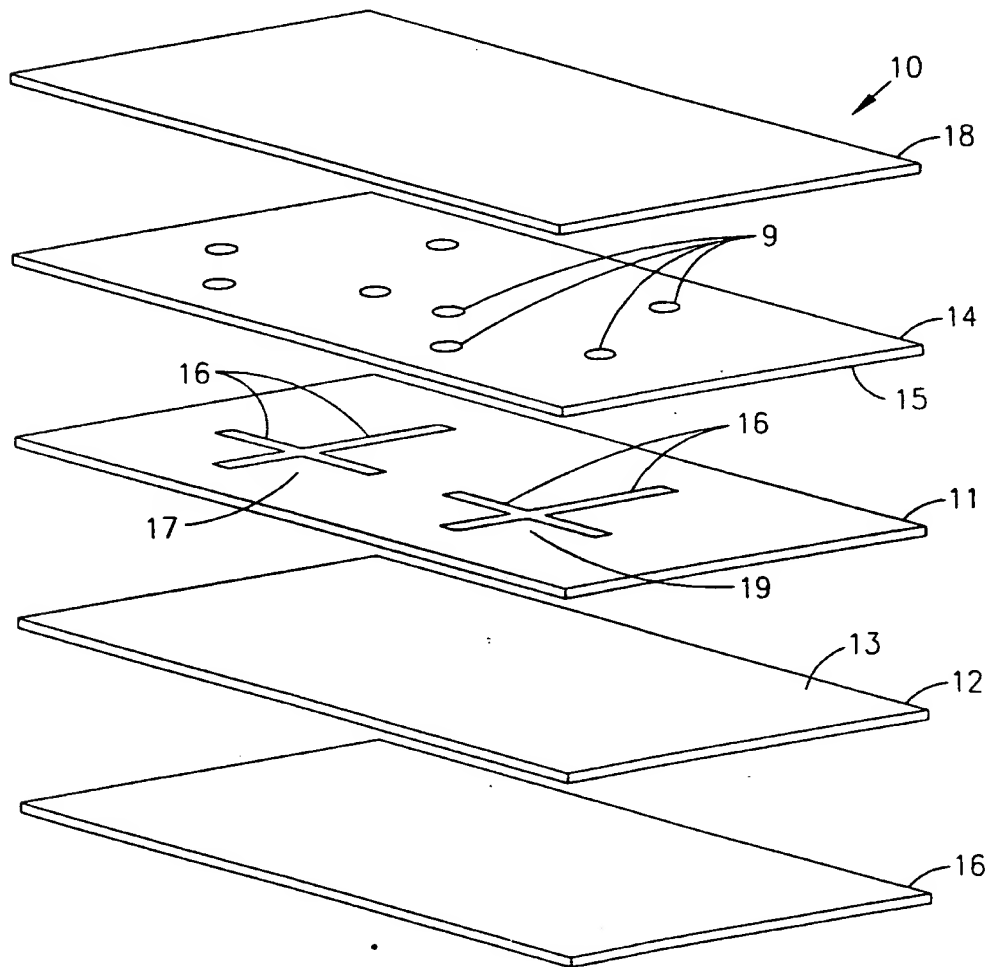


FIG. 1B

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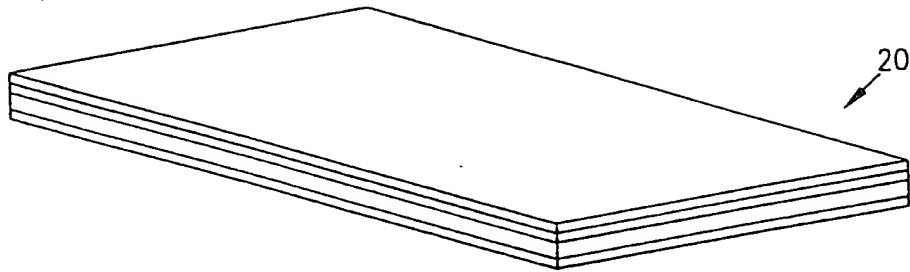


FIG. 2A

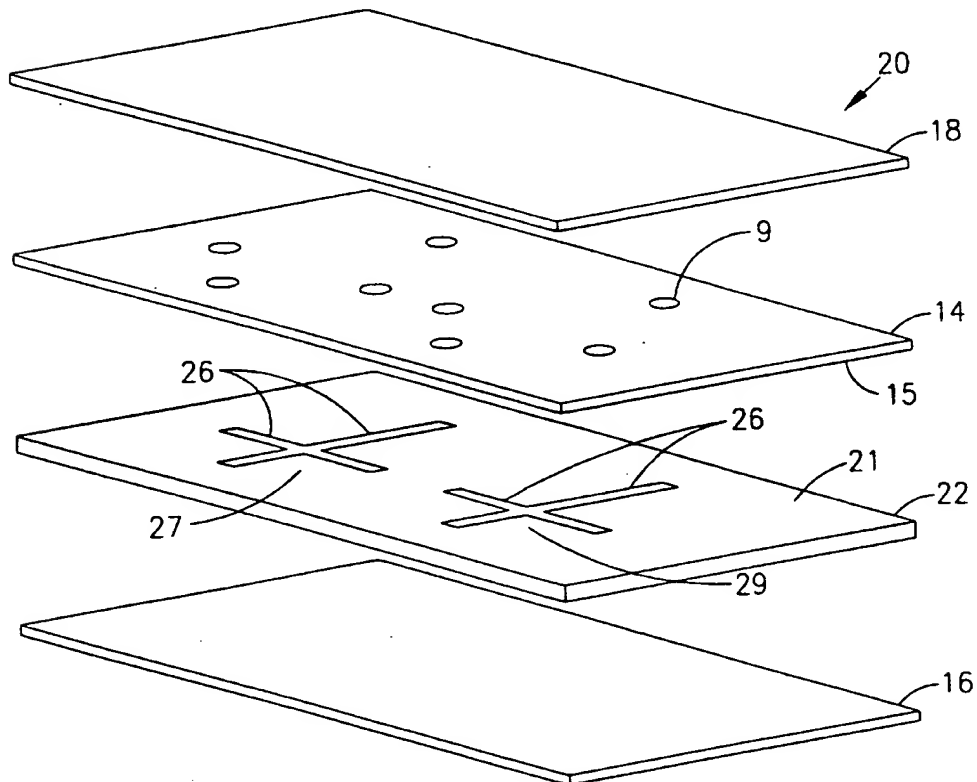


FIG. 2B

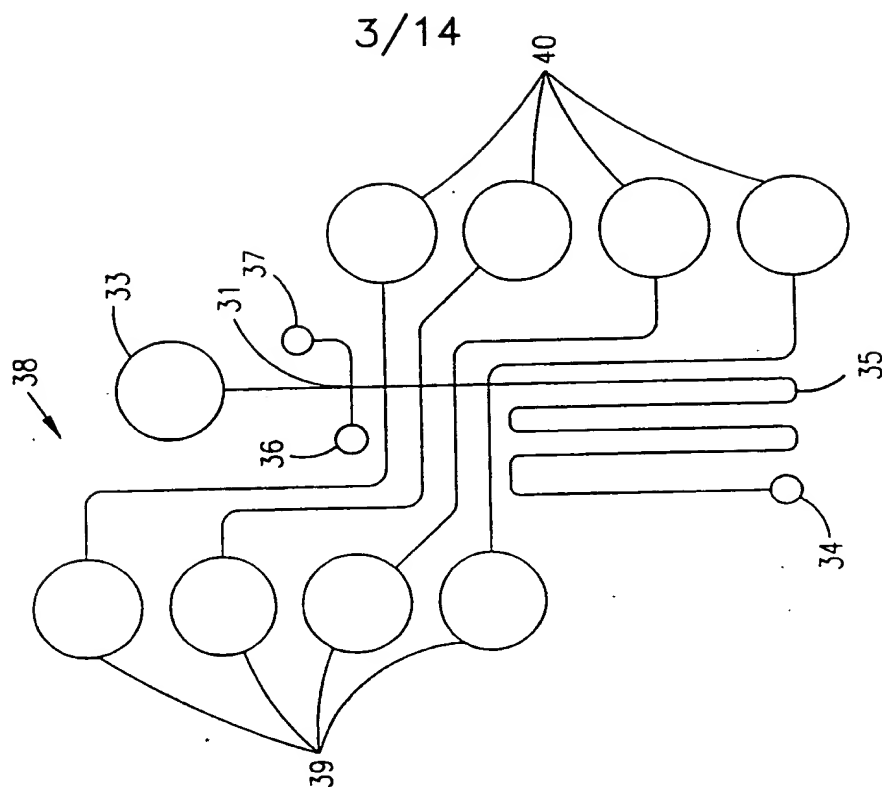


FIG. 3C

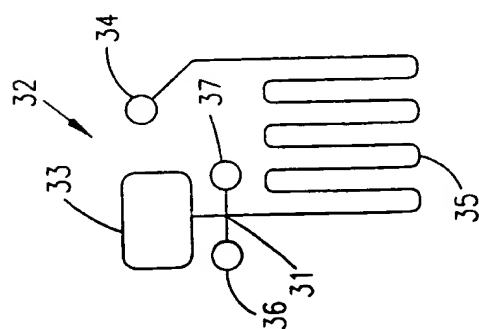


FIG. 3B

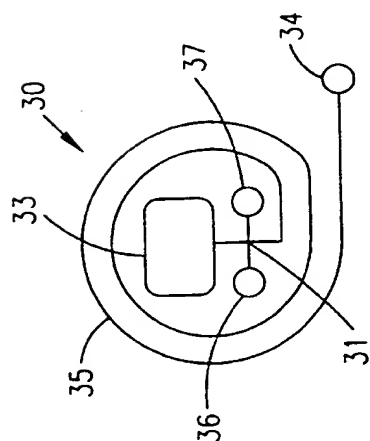


FIG. 3A

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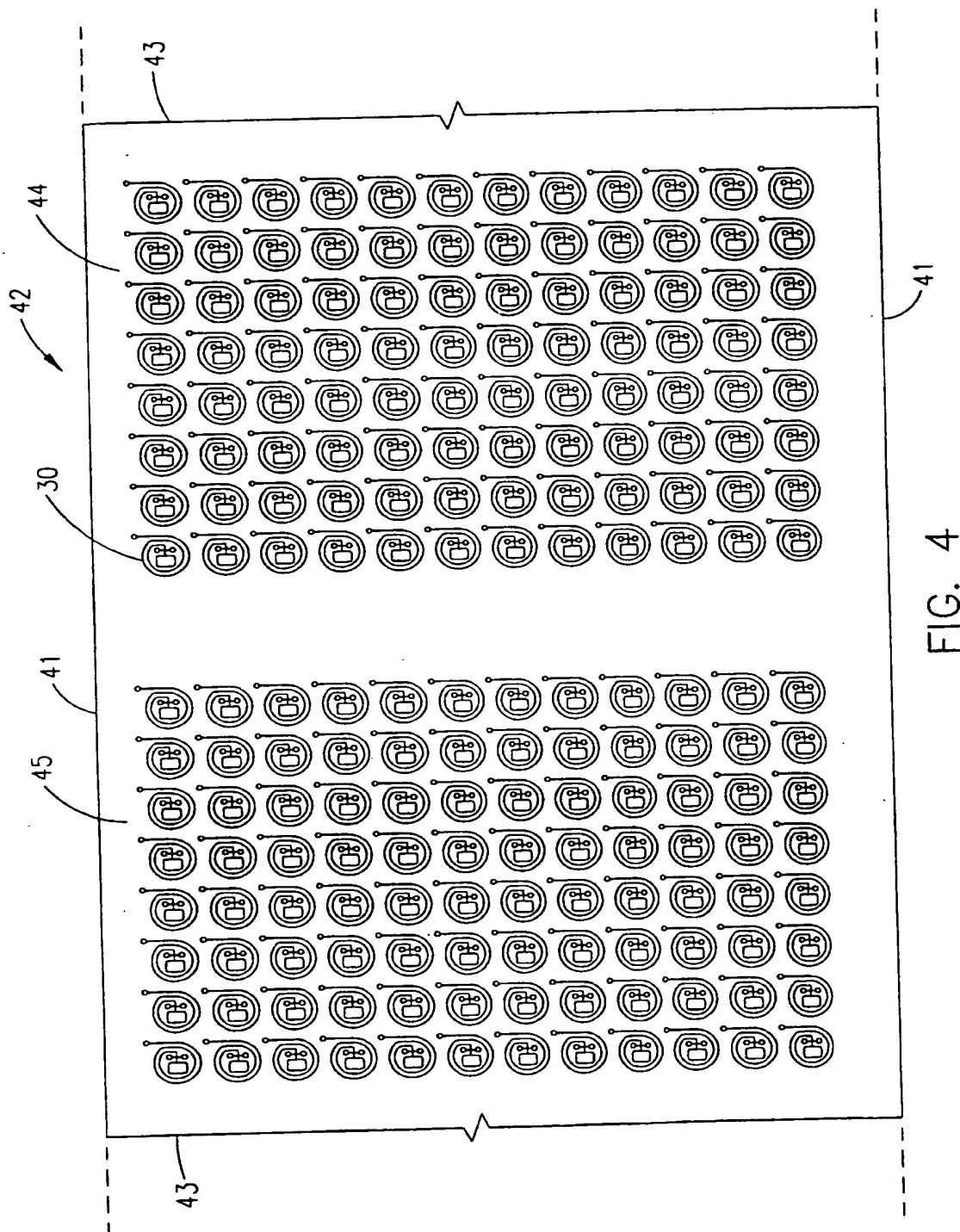


FIG. 4



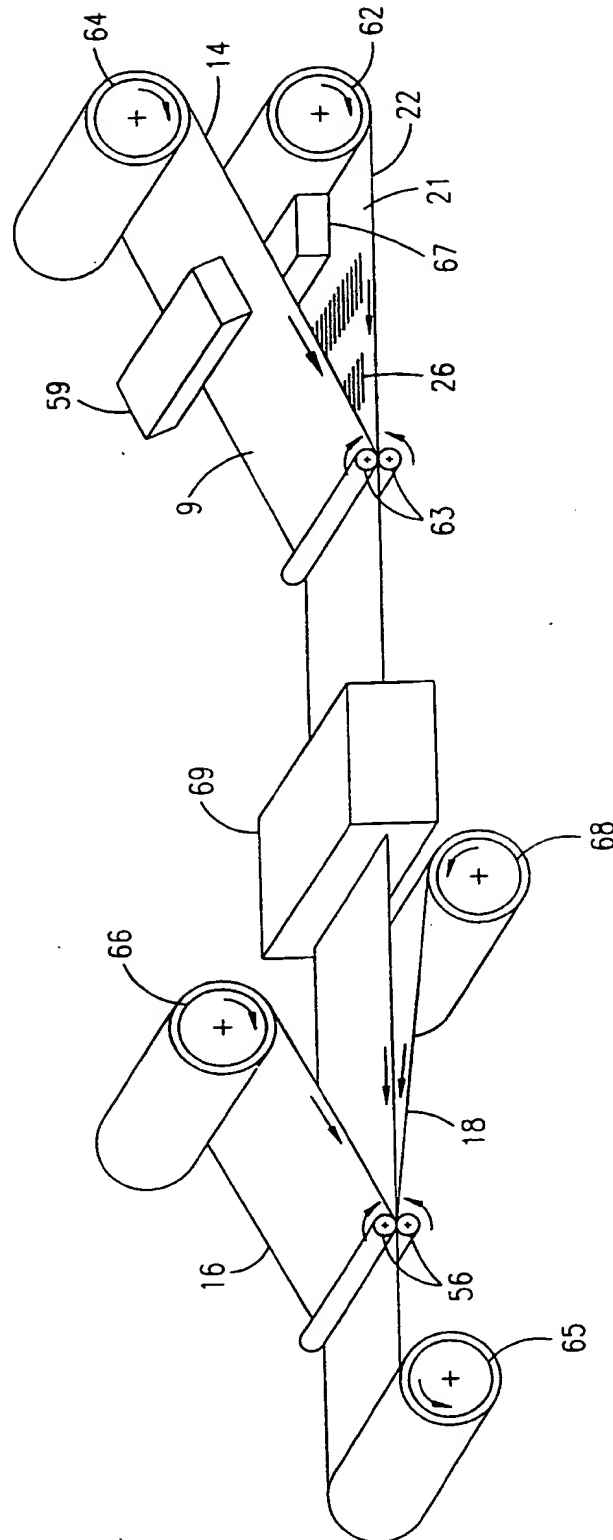


FIG. 6

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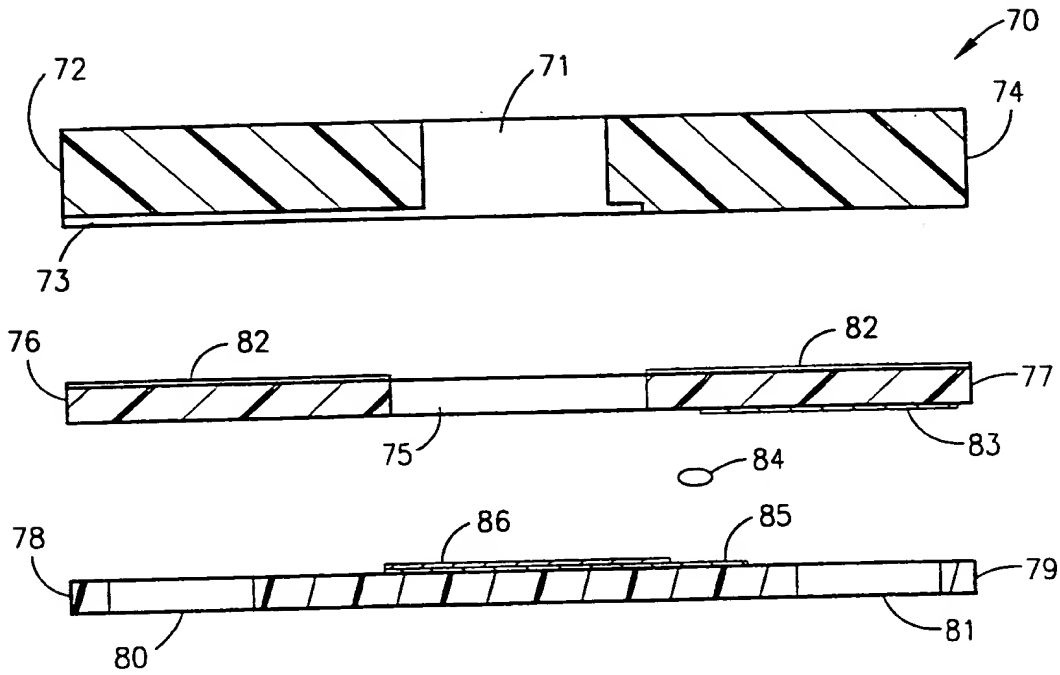


FIG. 7a

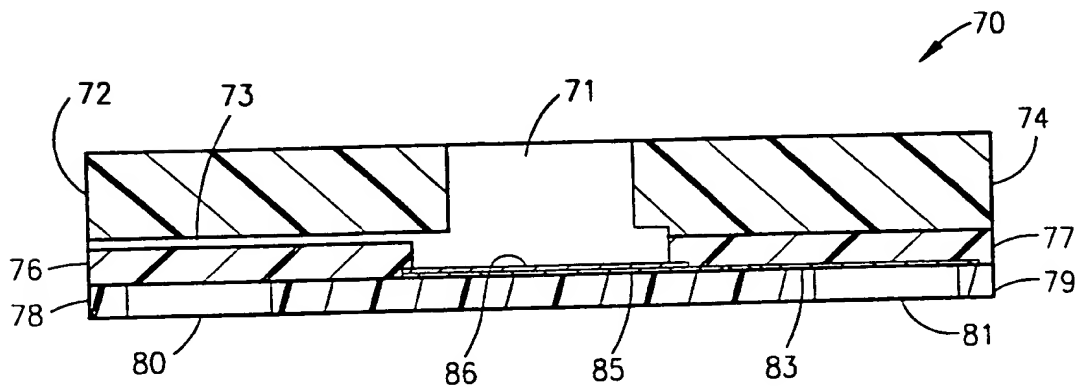


FIG. 7b



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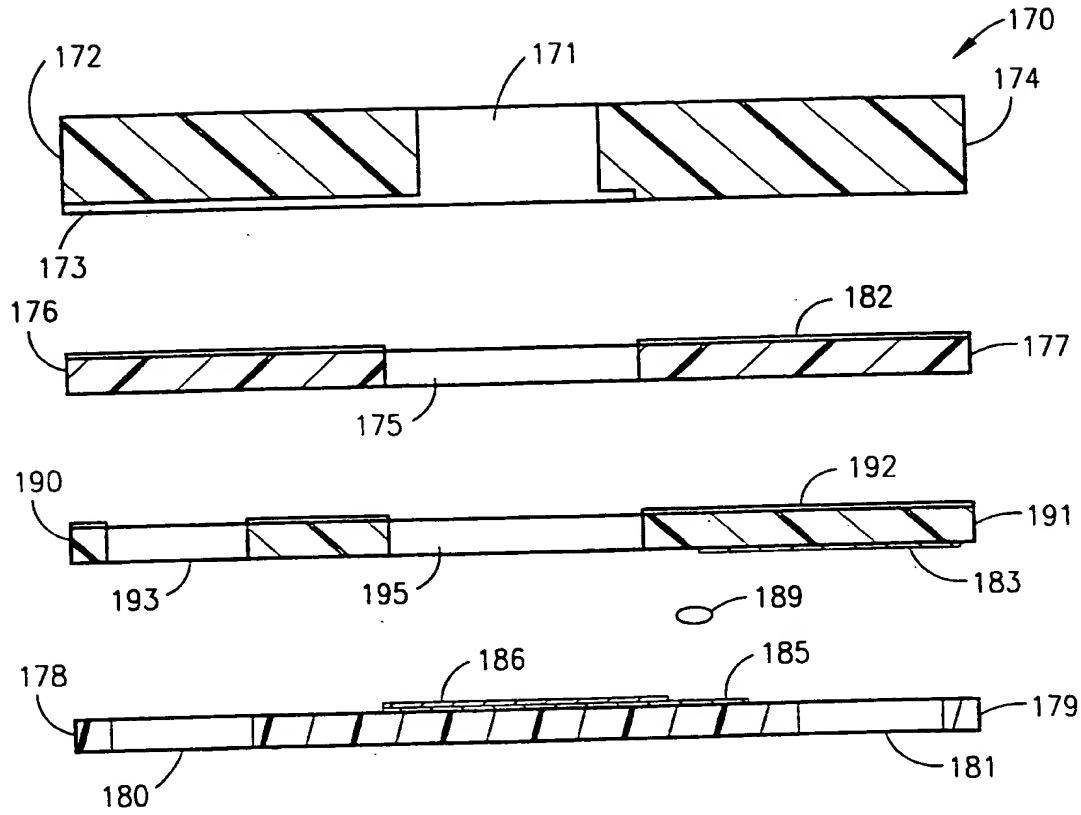


FIG. 8a

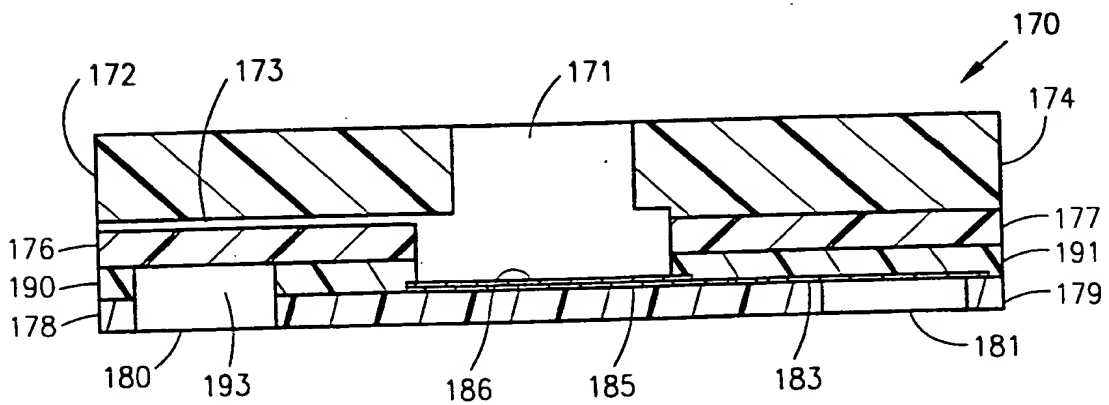


FIG. 8b





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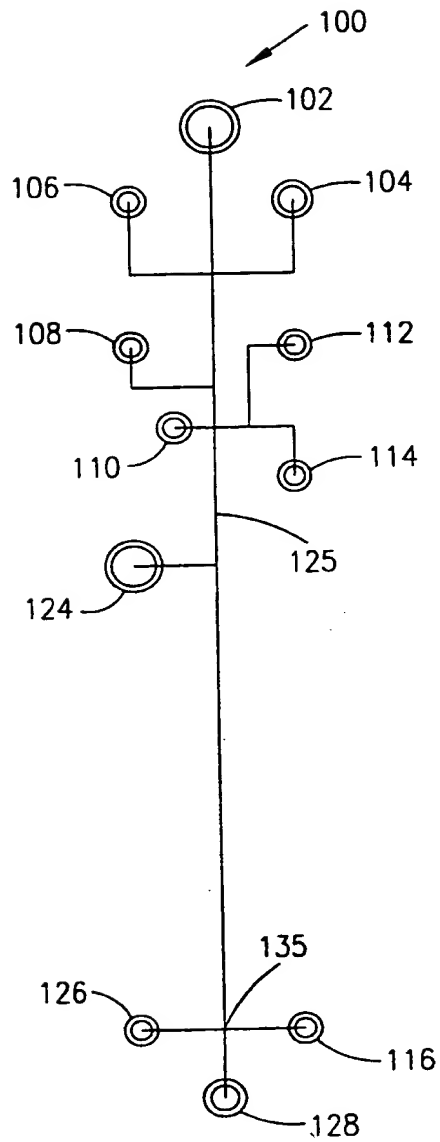


FIG. 9

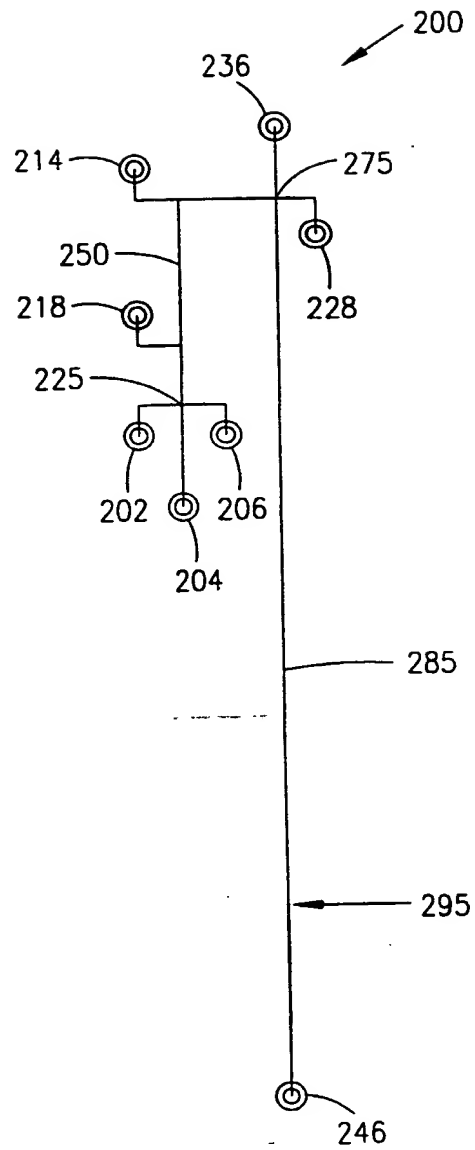


FIG. 10

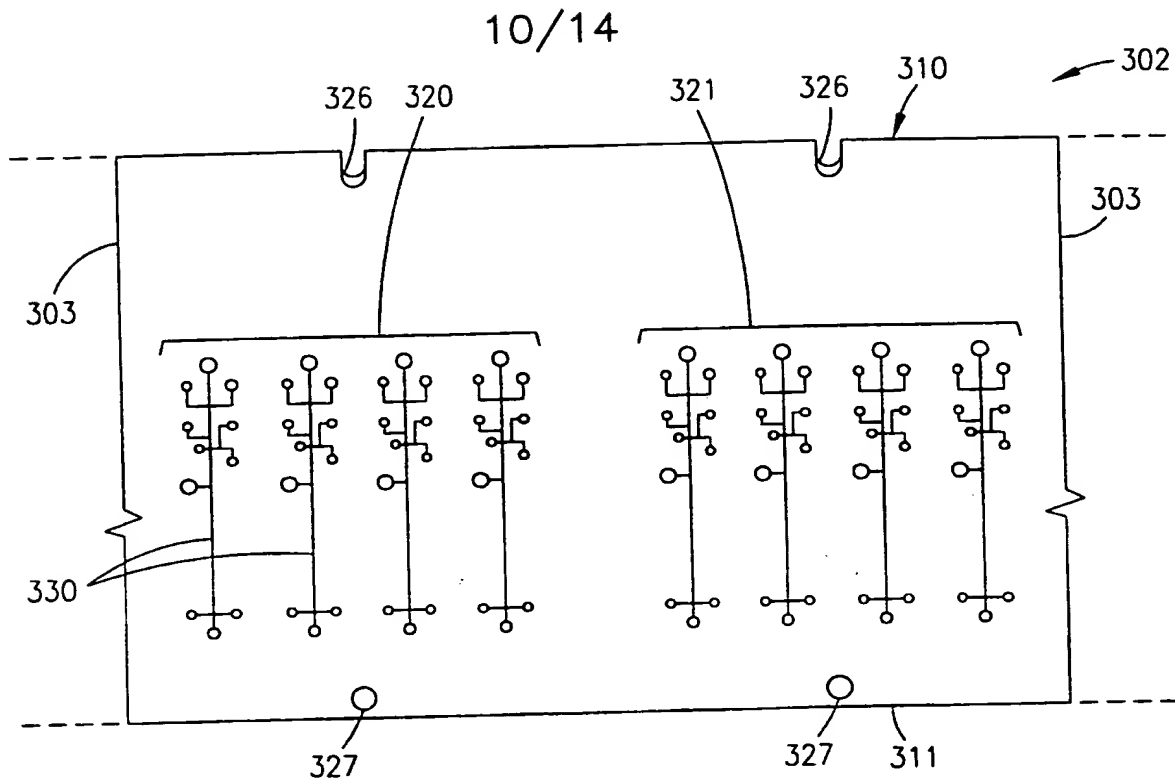


FIG. 11a

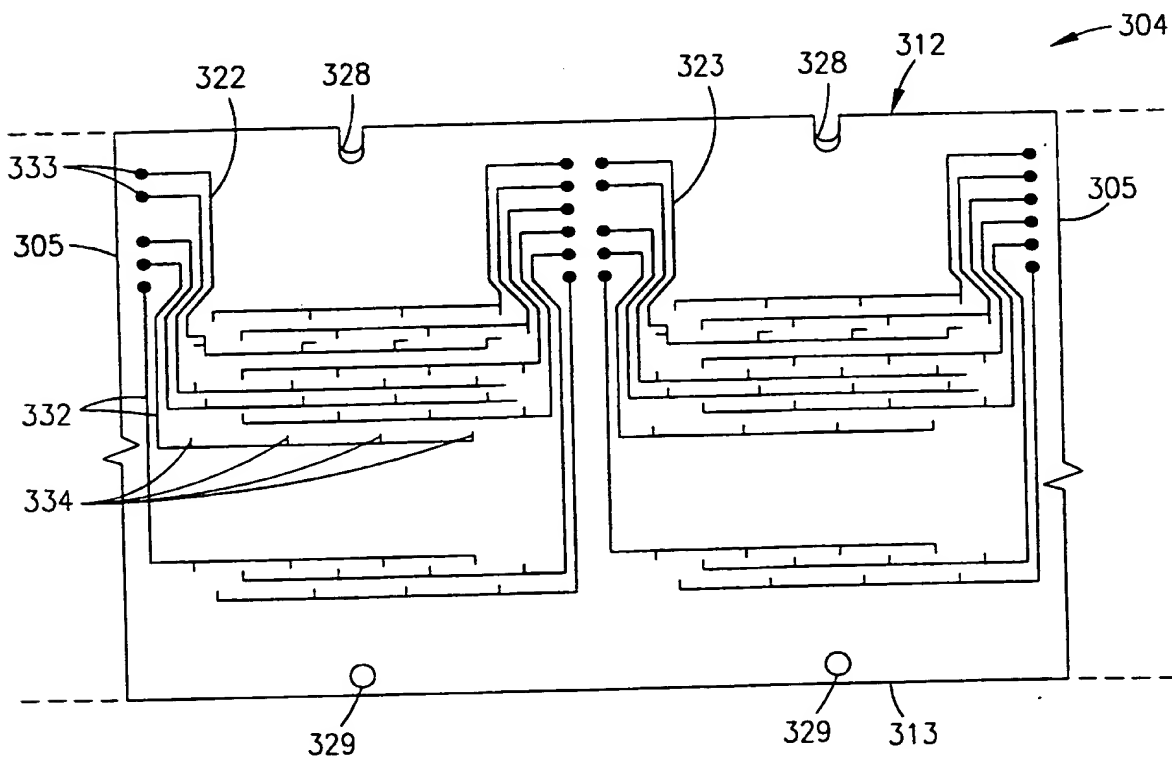


FIG. 11b

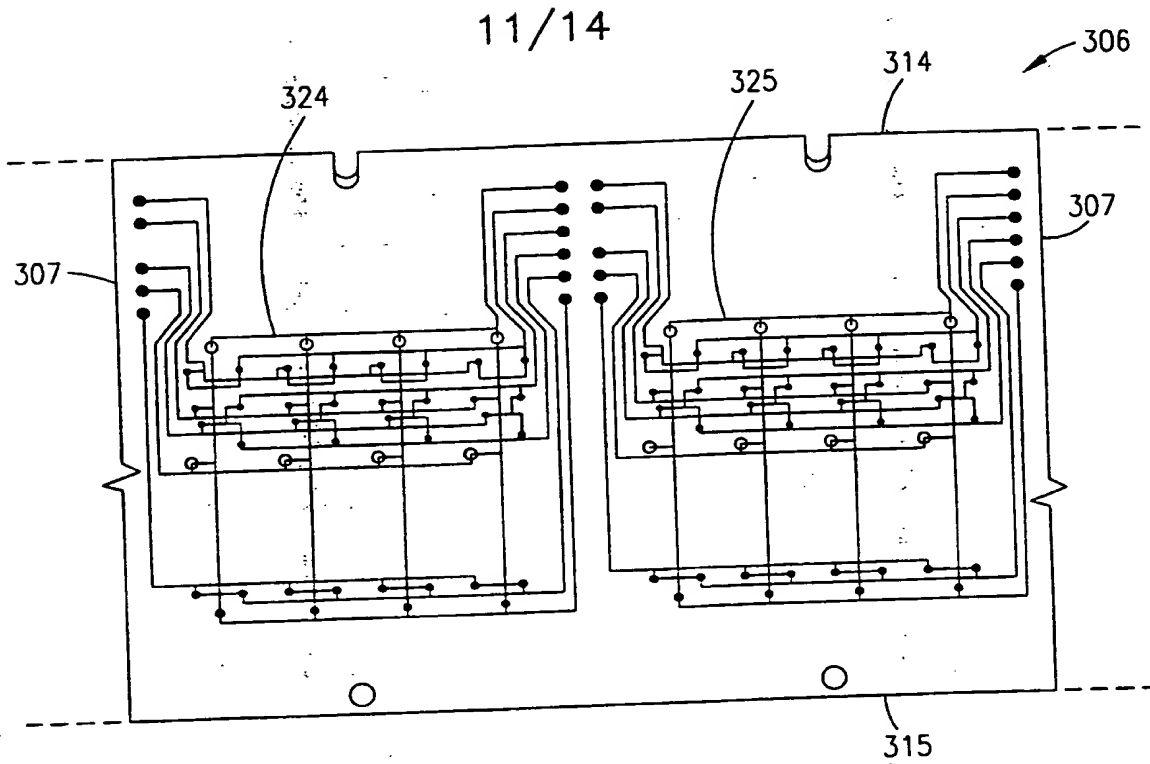


FIG. 11c

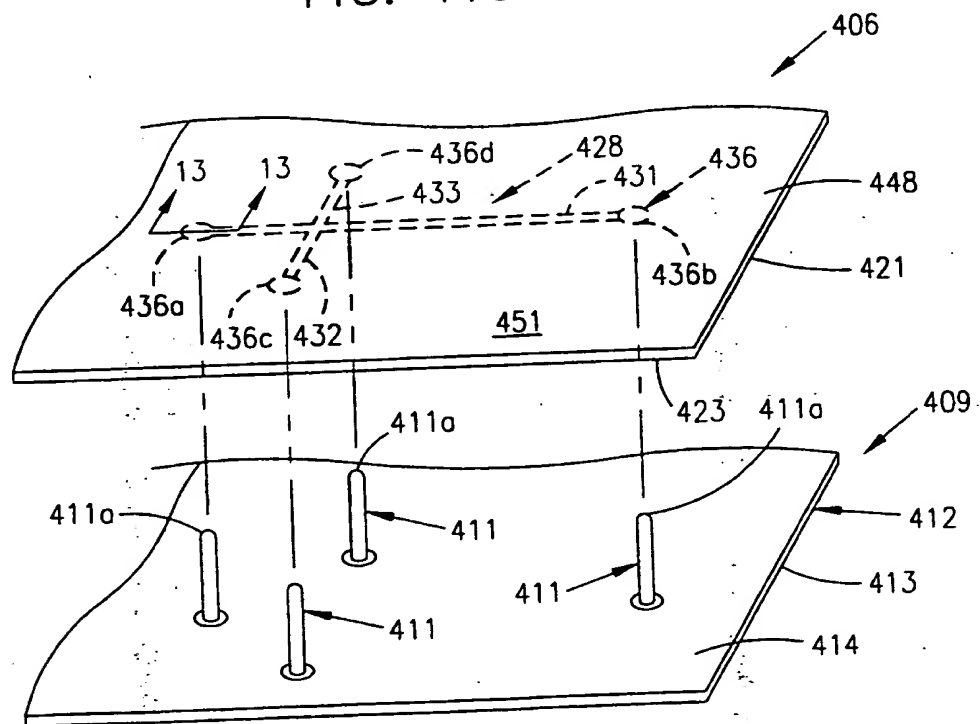


FIG. 12

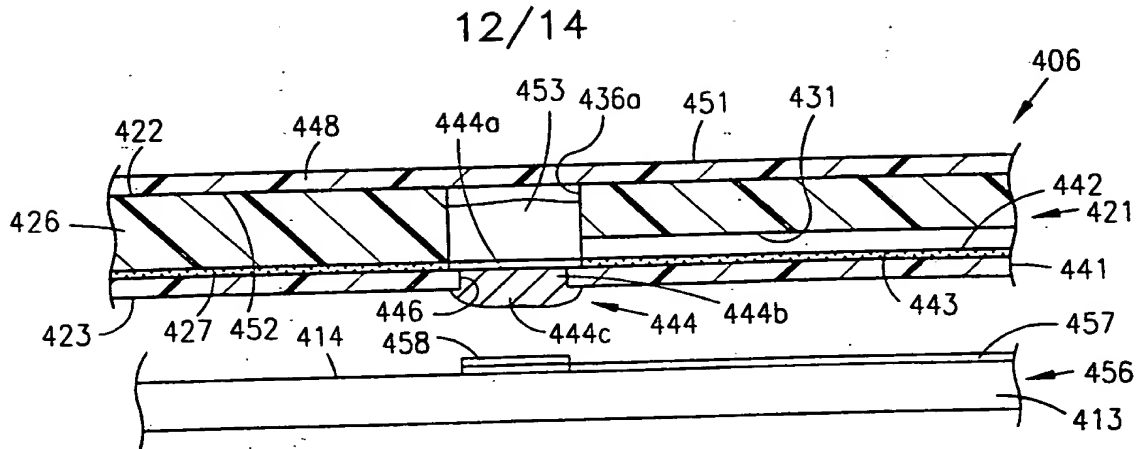


FIG. 13

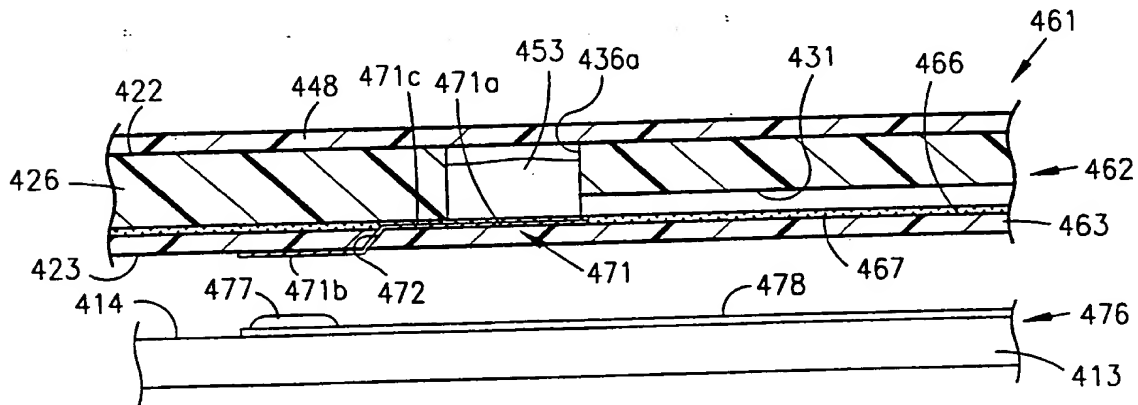


FIG. 14

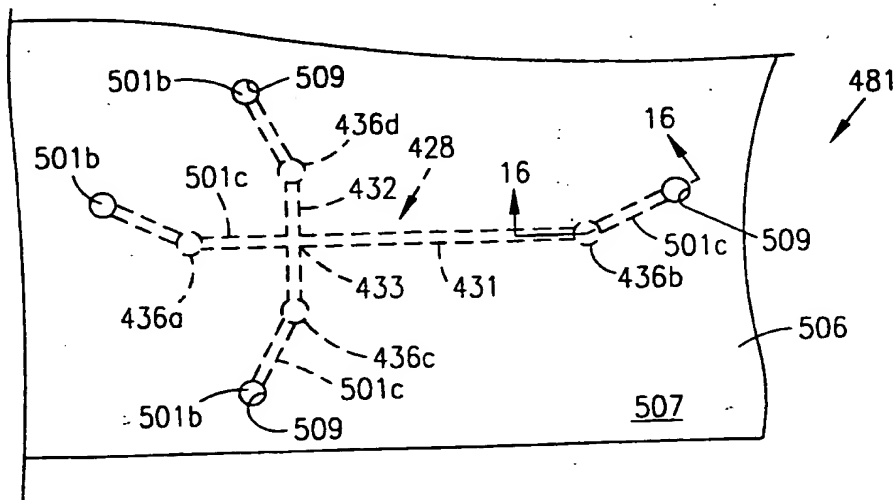


FIG. 15

A detailed cross-sectional diagram of a semiconductor device. The structure consists of several stacked layers. From top to bottom, there are layers labeled 553, 609, 596b, 617, 612, 596, 611, 596c, 561a, 591, 453, 607, 601, 621, 552, 586, 566, and 531. On the left side, additional labels include 604, 587, 567, 558, and 557. A central vertical feature is labeled 613. Other features include 554, 603, 568, 589, 588, 569, 576a, 576c, and 411a (which points to a small circular feature at the top). Arrows indicate specific regions or interfaces within the stack.

**SUBSTITUTE SHEET (RULE 26)**

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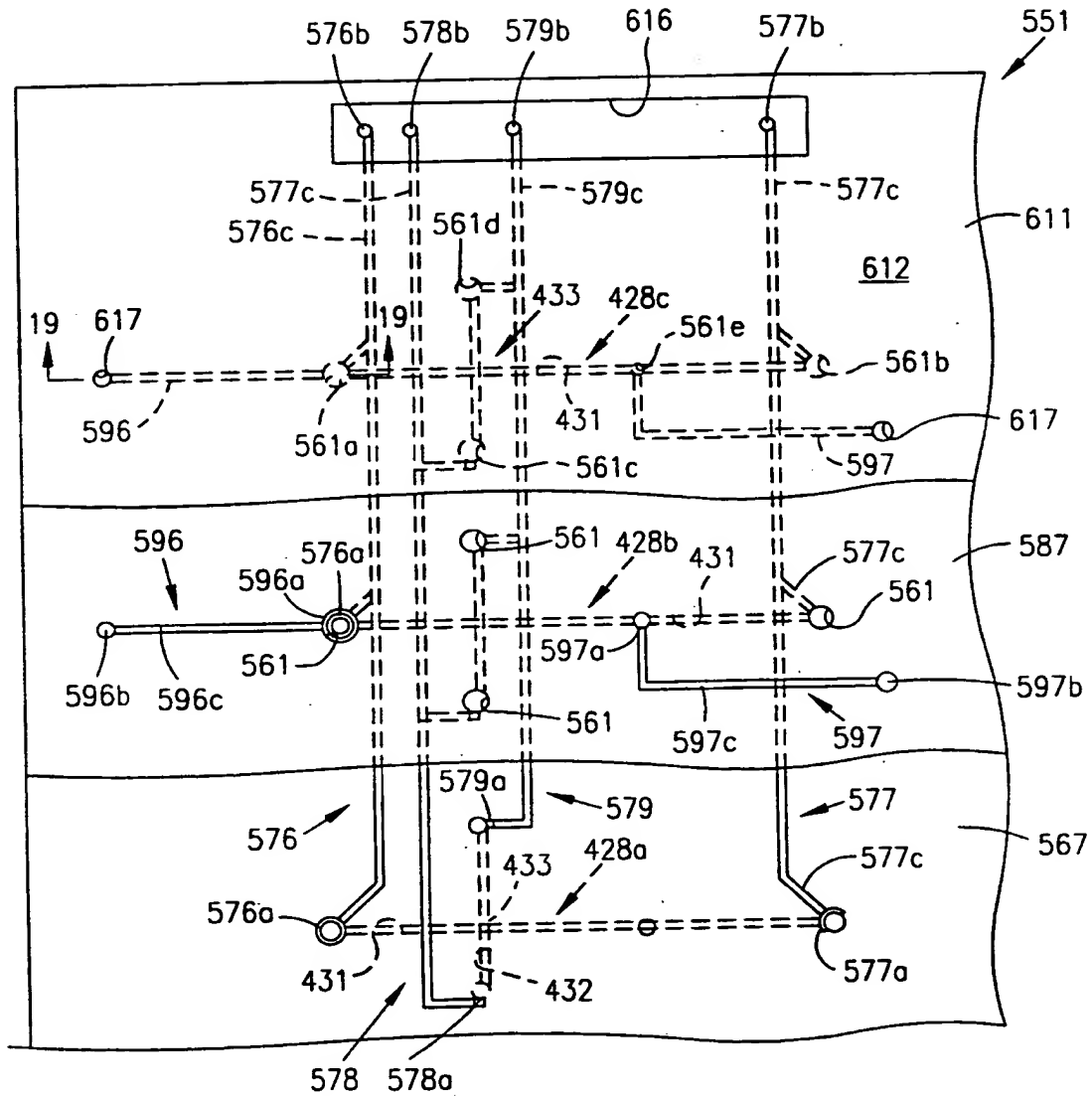


FIG. 18